

Market News

Best-in-class in price and performance: 600 V CoolMOS™ S7 superjunction MOSFET for low-frequency applications

Munich, Germany - March 2, 2020 - Infineon Technologies AG (FSE: IFX / OTCQX: IFNNY) develops solutions for highest efficiency and quality requirements. The newly launched [600 V CoolMOS™ S7](#) product family leads the way for power density and energy efficiency for applications where MOSFETs are switched at a low frequency. The key features of the CoolMOS S7 product family include optimization for conduction performance, improved thermal resistance, and high-pulse current capability, all of these at the highest quality standards. Applications for the devices are i.e. active bridge rectification, inverter stages, PLCs, [power solid-state relay](#) and solid-state circuit breakers. Furthermore, the 10 mΩ CoolMOS S7 MOSFET is the industry's smallest $R_{DS(on)}$ device.

The product family has been developed to minimize conduction losses and ensure the fastest response time together with increased efficiency for low-frequency switching applications. CoolMOS S7 devices deliver even lower $R_{DS(on)} \times A$ compared to CoolMOS 7 products to successfully trade off switching losses for lower on-resistance and lower cost. The CoolMOS S7 products come with the lowest on-resistance ($R_{DS(on)}$) in the market for a high-voltage switch. Additionally it has been achieved to fit the 10 mΩ chip into an innovative top side cooled QDPAK, and the 22 mΩ chip into a state-of-the-art small TO-leadless (TOLL) SMD package. These MOSFETs enable cost-effective, simple, compact and modular high-efficiency designs. Systems can easily meet regulations and energy efficiency certification standards (i.e., Titanium® for SMPS) as well as fulfill power budgets and reduce part count, heat sinks and total cost of ownership (TCO).

Availability

The 22 mΩ 600 V CoolMOS S7 device is available in TO-leadless and TO-220, the 40 mΩ and 65 mΩ devices are available in TO-leadless packages. The 10 mΩ CoolMOS S7 MOSFET will be on stock in Q4 2020. More information is available at www.infineon.com/s7.

For the Trade Press: INFPM200203.034e

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